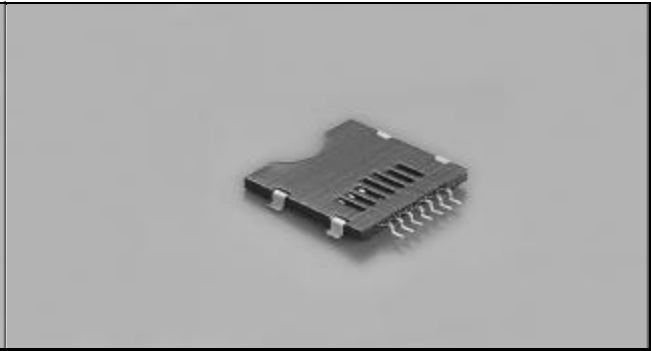


SMART CARD CONN



MMC CONN



SSFDC



SSFDC PUSH TYPE

**MATERIALS/FINISHES**

**INSULATOR**

THERMOPLASTIC ( UL94V-0 )

**CONTACT**

PHOSPHOR BRONZE

CONTACT AREA:

GOLD OVER Ni ( 50 90u" )

SOLDER AREA:

TIN/LEAD ( 100 200u" ) OVER Ni

**SHELL**

STEEL

Ni PLATING

**SPECIFICATION**

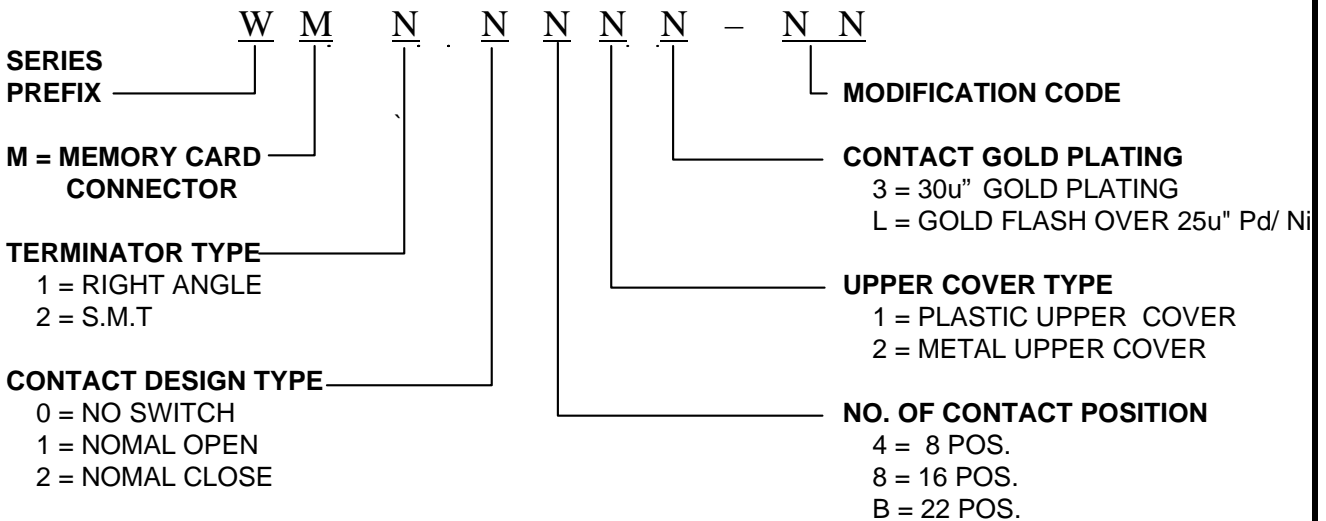
**ELECTRICAL CHARACTERISTICS :**

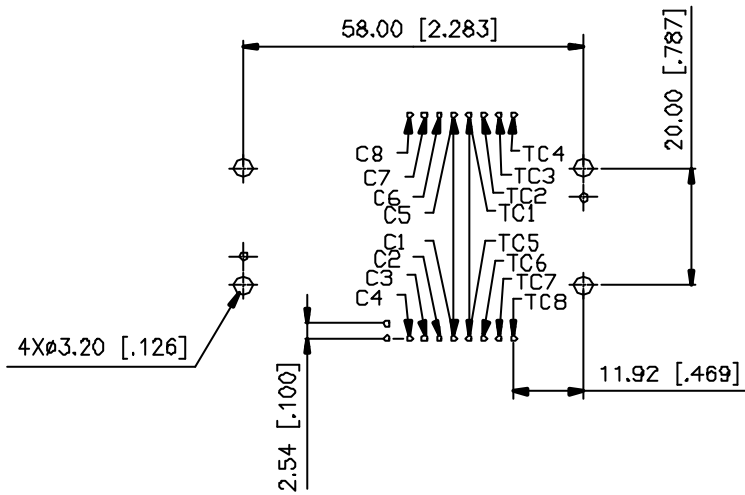
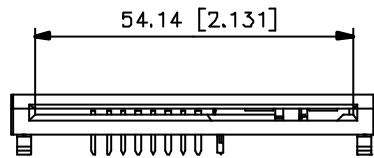
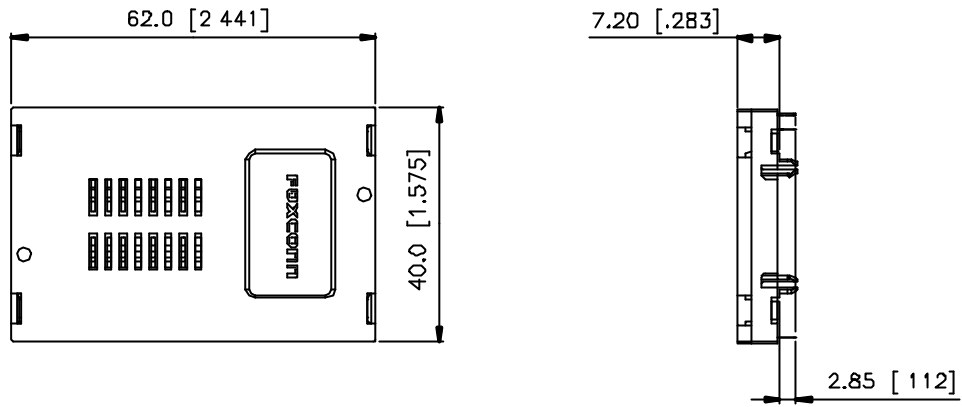
- \* LOW LEVEL CONTACT RESISTANCE : 40 m MAX.
- \* DIELECTRIC WITHSTANDING VOLTAGE : 500 VAC MIN.
- \* INSULATION RESISTANCE : 1000 M MIN.
- \* CONTACT CURRENT RATING : 1.5 Ampere

**MECHANICAL CHARACTERISTICS :**

- \* CONNECTOR INSERTION FORCE : 4 oz. MAX.
- \* CONNECTOR EXTRACTION FORCE : 0.6 oz. MAX.
- \* DURABILITY : 10000 CYCLES
- \* OPERATING TEMPERATURE : -20 TO +60

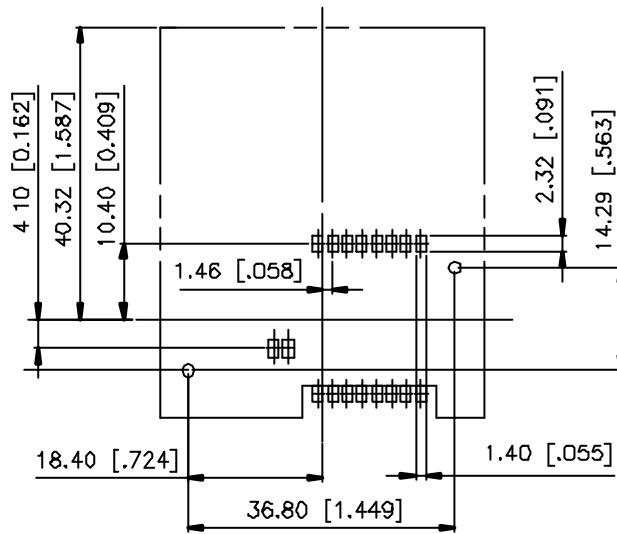
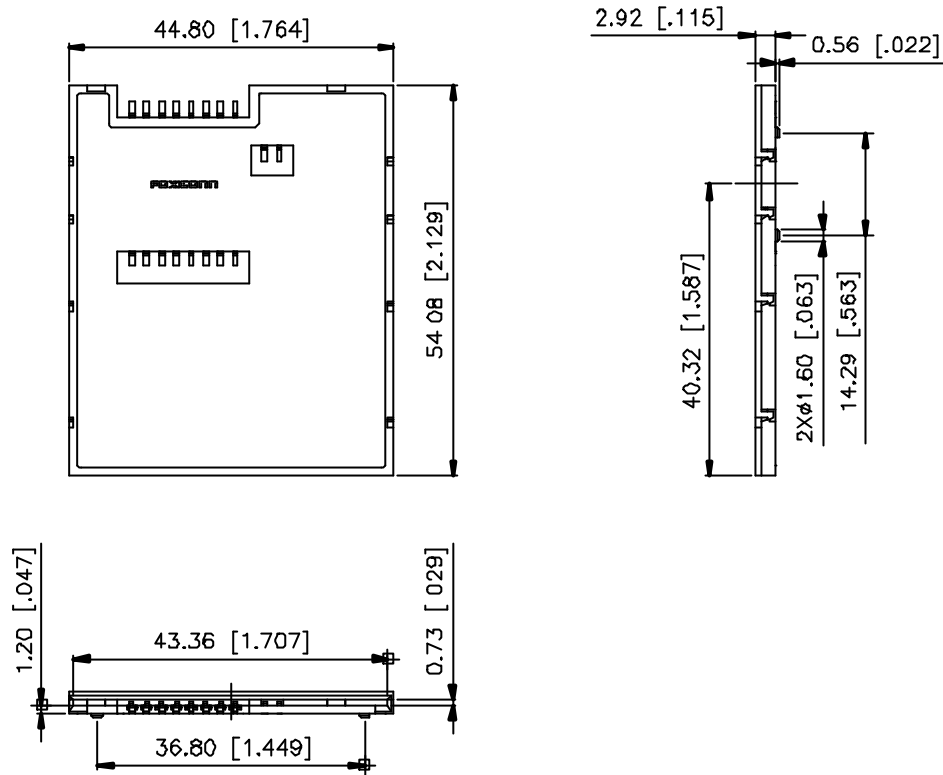
**ORDER INFORMATION**





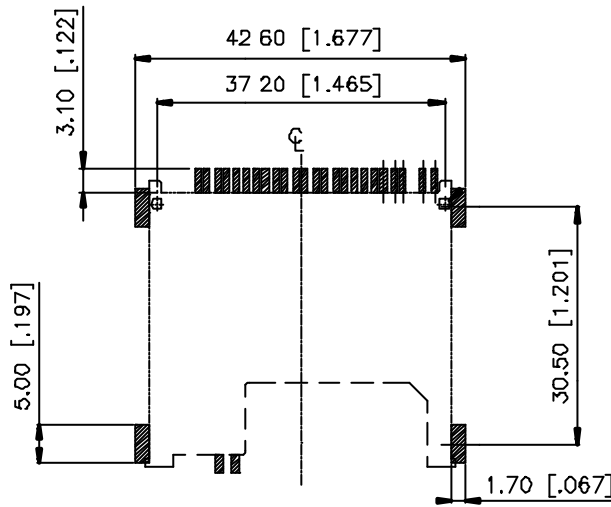
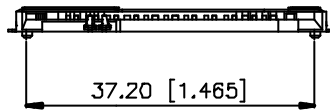
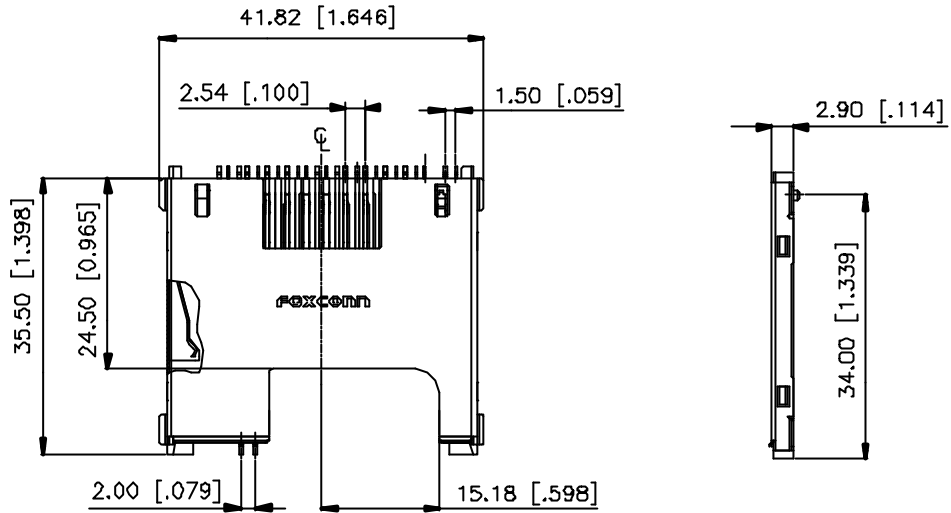
**RECOMMENDED P.C.B LAYOUT**  
**(TOP VIEW)**

<b>PROD. NO.</b>	<b>WM1241L-P2</b>
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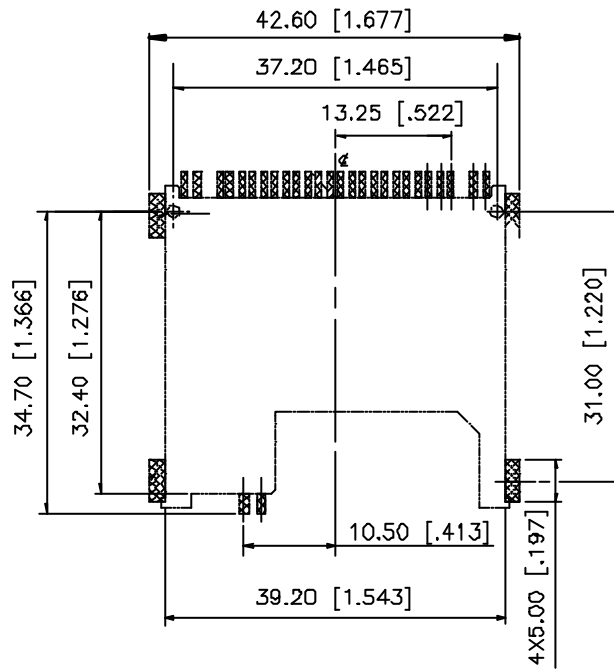
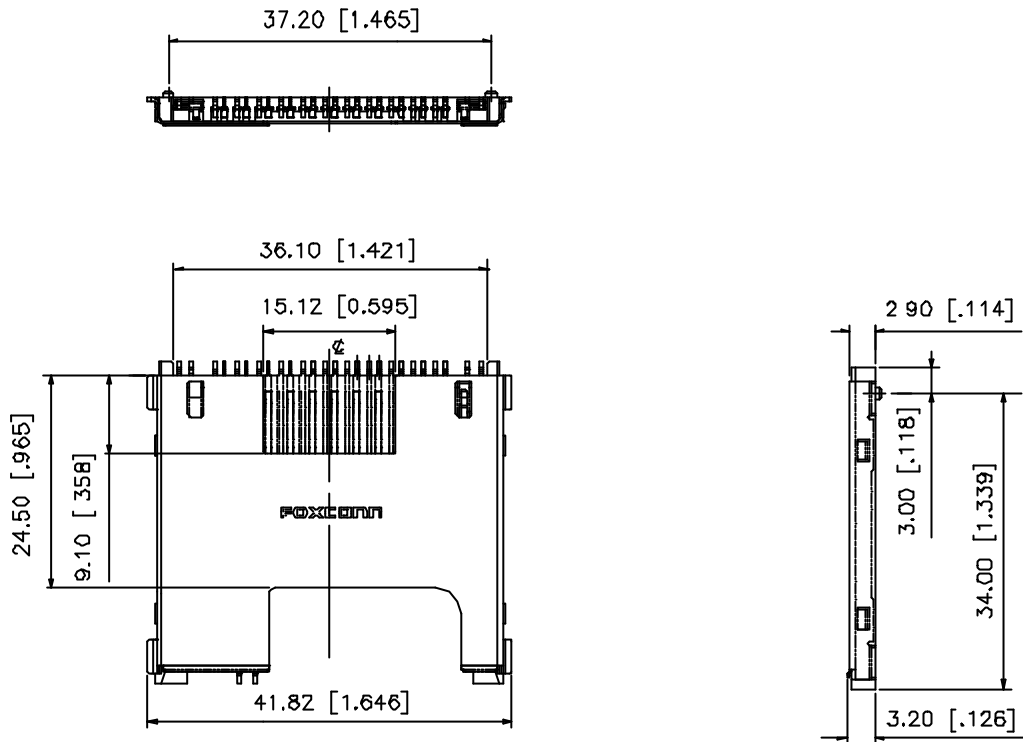
**RECOMMENDED P.C.B LAYOUT**  
**(BOTTOM VIEW)**

<b>WM2181L-P4</b>	<b>18 POS.</b>
<b>PROD. NO.</b>	<b>NO. OF POS.</b>



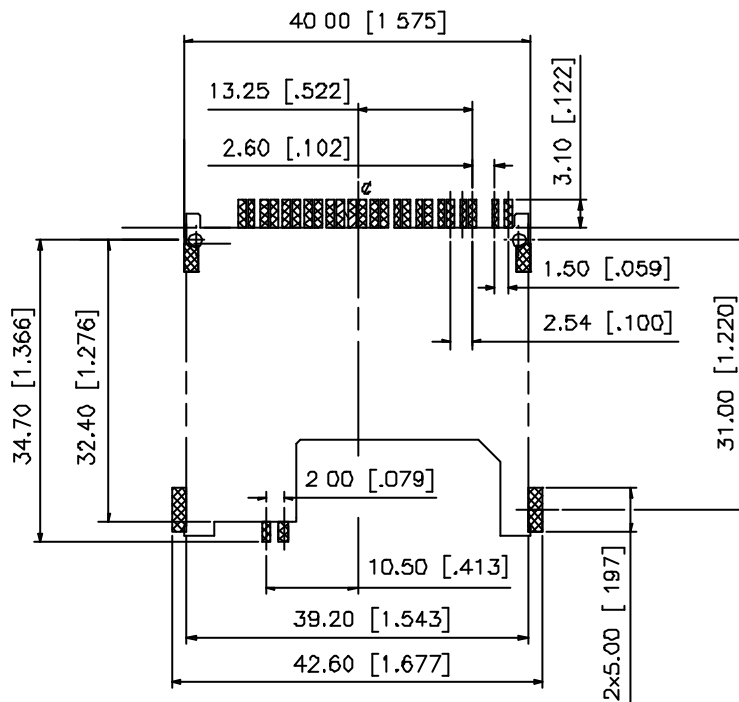
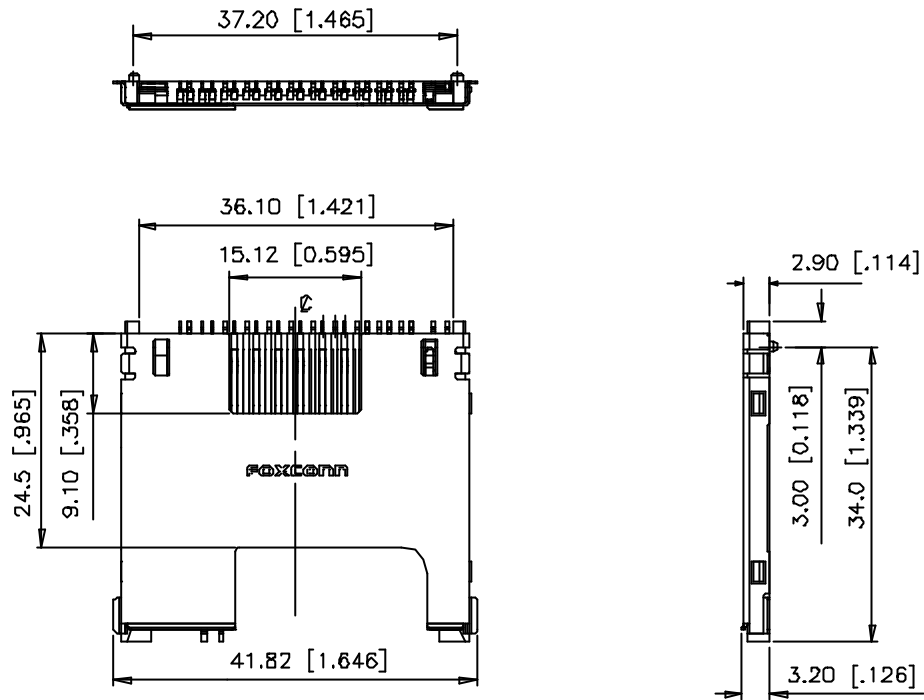
**RECOMMENDED P.C.B LAYOUT**  
**(TOP VIEW)**

<b>PROD. NO.</b>	<b>WM21B23-R0</b>
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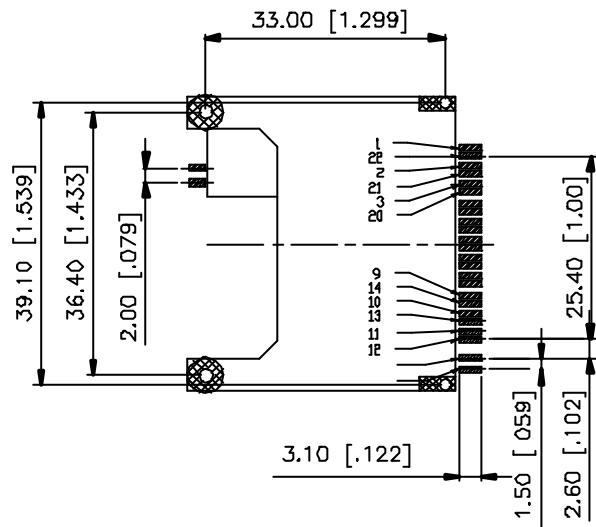
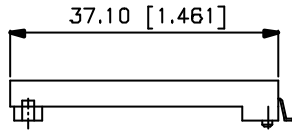
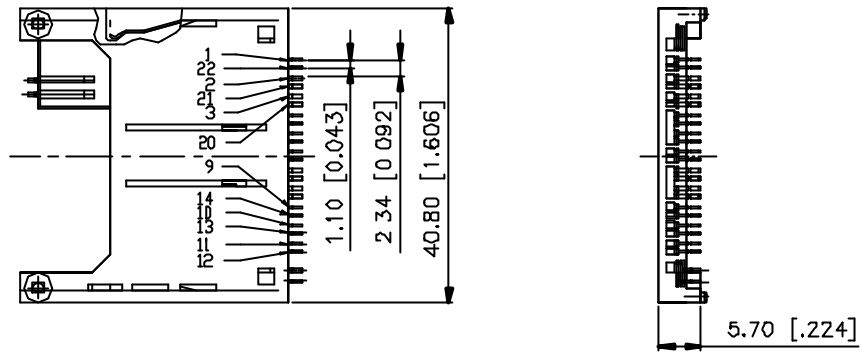
**RECOMMENDED P.C.B. LAYOUT  
(TOP VIEW)**

<b>WM21B23-R4</b>	<b>22 POS.</b>
<b>PROD. NO.</b>	<b>NO. OF POS.</b>



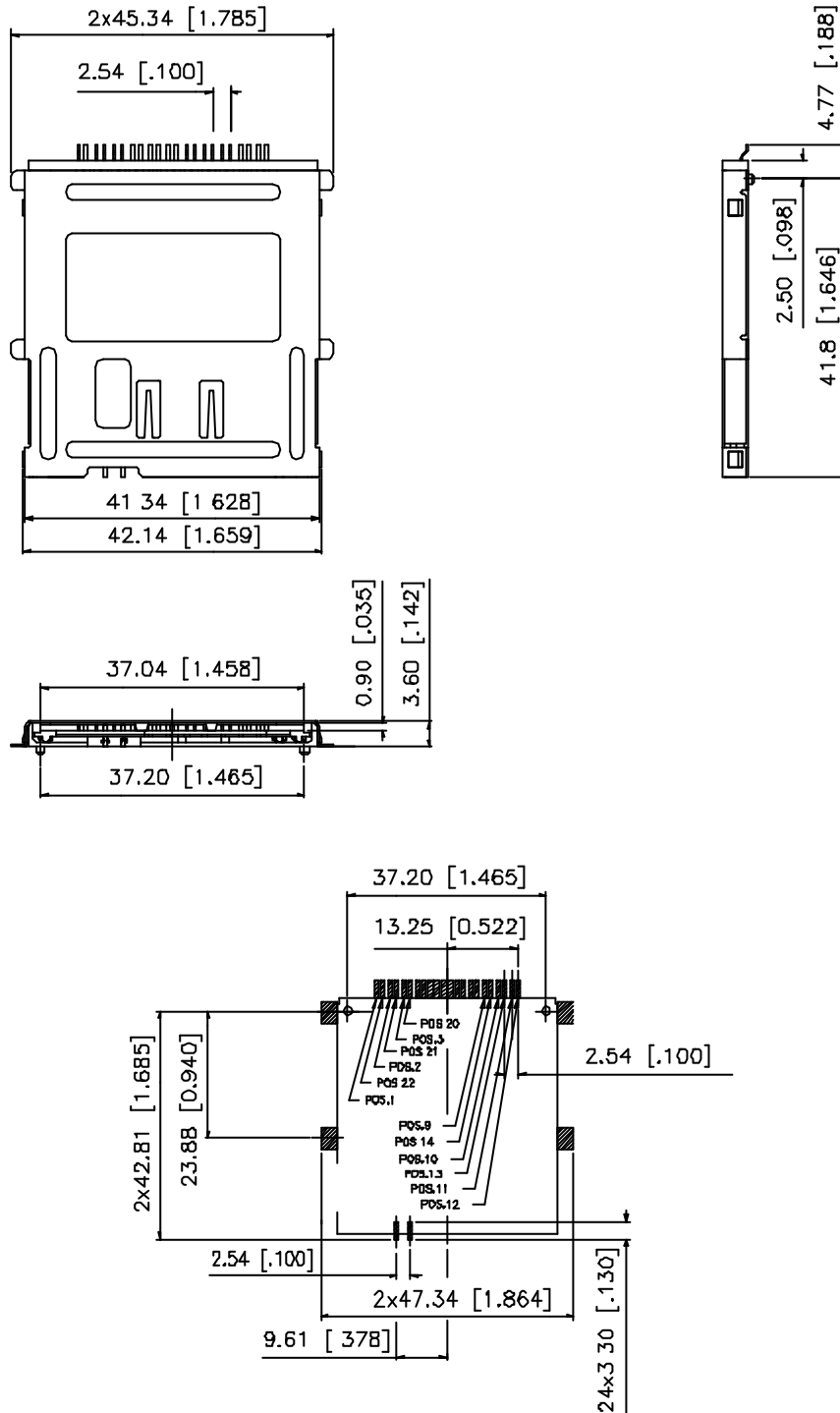
**RECOMMENDED P.C.B LAYOUT**  
**(BOTTOM VIEW)**

<b>WM21B23-R11</b>	<b>22 POS.</b>
<b>PROD. NO.</b>	<b>NO. OF POS.</b>



**RECOMMENDED P.C.B LAYOUT**  
**(TOP VIEW)**

<b>WM21B13-R2</b>	<b>22 POS.</b>
<b>PROD. NO.</b>	<b>NO. OF POS.</b>



**RECOMMENDED P.C.B LAYOUT**  
**(TOP VIEW)**

<b>WM20B23-A0</b>	<b>22 POS.</b>
<b>PROD. NO.</b>	<b>NO. OF POS.</b>